JFP Model PP5-7



REWORK STATION



The model PP5-7 Rework Station is designed for accurate Die Removal, Bond Area Planner, Solder Balls Removal and Local Vacuum Cleaner, with outstanding accurate **Placement** capability of delicate Devices on Substrate or deep Packages. (Optional Flip).

Pick and Place from Wafer, from Waffle Pack, Gel-Pak or bulk Die media . PP5-7 achieves a placement accuracy better than $<5\mu m$.

Efficient Die Remover system, with Dual Action, including local Hot Gaz and adjustable Shear Effect, compatible with very small Dies (<200µm), in very high density Hybrid Devices.

Adjustable Routine for solder Balls removal, for Surface Planner and Vacuum Cleaner.

A robust, and reliable mechanical concept, designed to be external vibration free.

Easy to use, flexible, the PP5-7 requires only minimum training to operate

- PC and microcontroller
- Frame Vibration free

DIE & SUBSTRATE

- Minimum die size 150*200µm
- Maximum die size 20*20mm. Option more
- Substrate Up to 300 mm standard.

VISION SYSTEM

- Field of view 1,2 mm or ZOOM
- CCD Color camera high resolution
- Digital Video Mixer (Flip Option)
- TFT monitor 17'
- Target generator
- LED lightings & pen light
- Direct placement
- 2 references points for auto-centering placement

XY TABLE

- Motorized X 260mm, Y 120mm / 1µm display
- Motion control with progressive joystick weight

PARAMETERS & DISPLAY

- TFT monitor
- Programmable force 10gr to 700gr Opt: Heavy duty Bond Head
- Programmable bond time
- Adjustable Cleaning Parameters
- Programmable Row for ball removal
- · Programmable line for Bond Surface Planner

OPTIONS

- Ultrasonic
- Dispenser
- Stamping
- Eutectic / Reflow
- Eject sytem for Wafer Sorter
- Hot gaz gun or micro jet hot gas.
- Heated chucks

TECHNICAL SPECIFICATION

Power: 100 / 230VAC 500watt

Vacuum: 70%

650*820*1450mm Dimensions:

Weight: 90kgr.